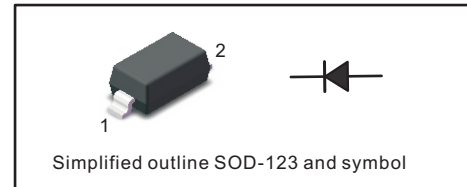


Silicon Planar Zener Diodes

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



FEATURES

- Total power dissipation: Max. 350mW.
- Wide zener reverse voltage range 1.8V to 43V.
- Small plastic package suitable for surface mounted design.
- Tolerance approximately $\pm 5\%$

MECHANICAL DATA

- Case: SOD-123
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 16mg/0.00056oz

Absolute Maximum Ratings And Characteristics (Ta = 25 °C)

Parameter	Symbol	Value	Unit
Power Dissipation	P_{tot}	350	mW
Forward Voltage at $I_F=10mA$	V_F	0.9	V
Typical thermal resistance junction to ambient ⁽¹⁾	$R_{\theta JA}$	340	$^{\circ}C/W$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^{\circ}C$

(1) Thermal resistance from junction to ambient at P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper areas pads.

Fig.1 Maximum Continuous Power Derating

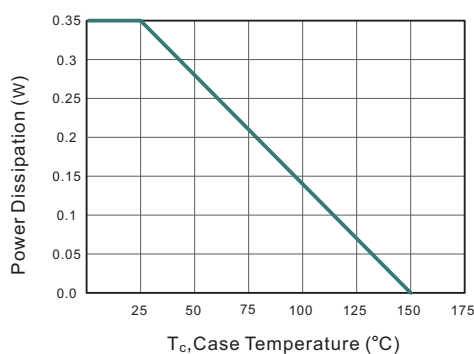
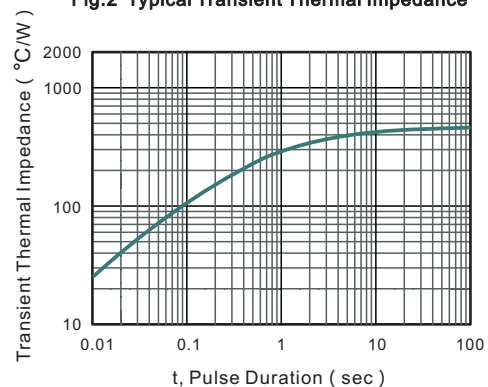


Fig.2 Typical Transient Thermal Impedance



Characteristics at Ta = 25°C

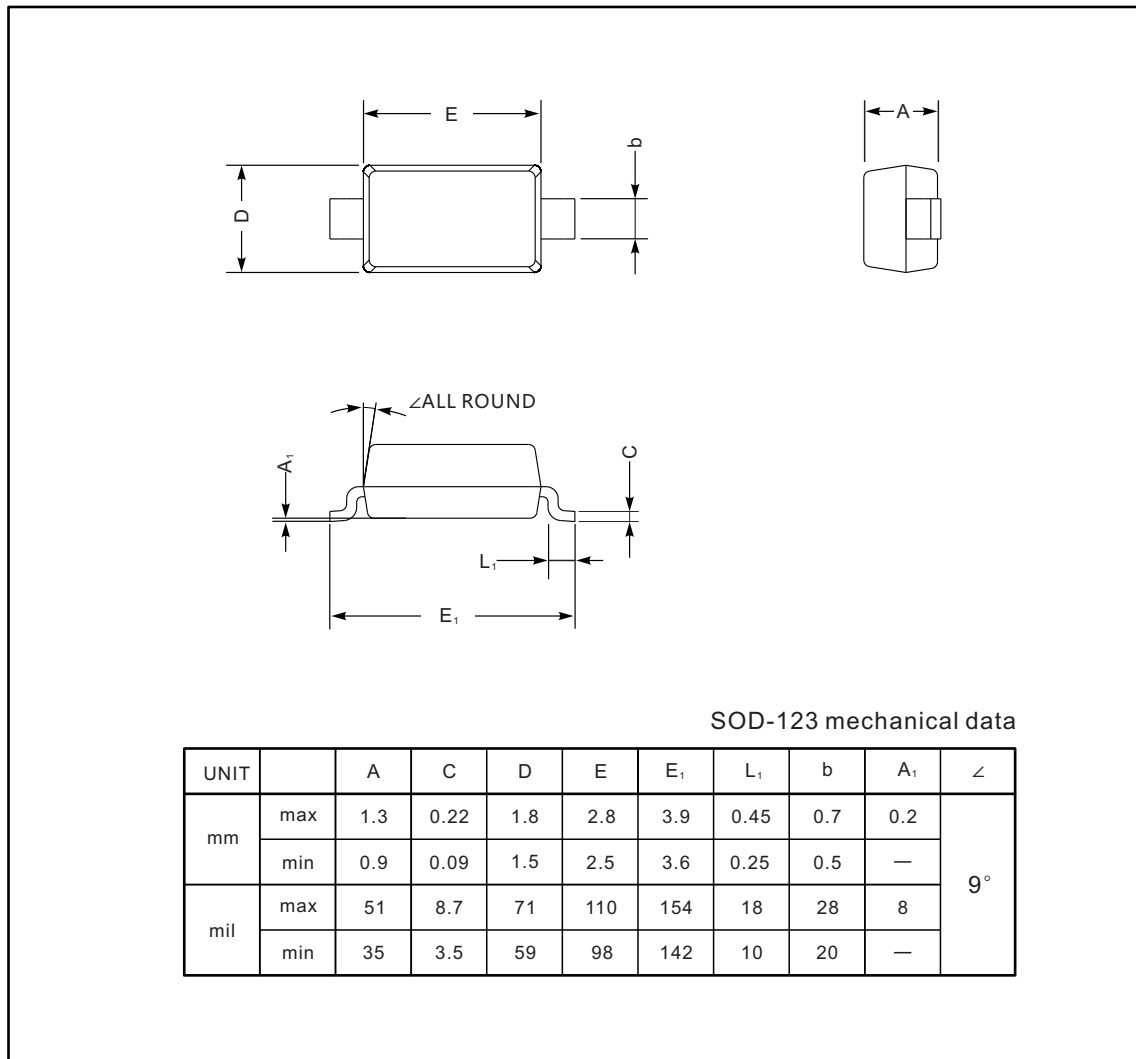
Type	Marking	Zener Voltage Range			I _{ZT}	Reverse Current	
		V _{ZT} (at I _{ZT})				I _R	at V _R
		Min (V)	Nom (V)	Max (V)	(μ A)	Max (μ A)	(V)
MMSZ4678	CC	1.71	1.8	1.89	50	7.5	1
MMSZ4679	CD	1.9	2.0	2.1	50	5	1
MMSZ4680	CE	2.09	2.2	2.31	50	4	1
MMSZ4681	CF	2.28	2.4	2.52	50	2	1
MMSZ4682	CH	2.57	2.7	2.84	50	1	1
MMSZ4683	CJ	2.85	3	3.15	50	0.8	1
MMSZ4684	CK	3.14	3.3	3.47	50	7.5	1.5
MMSZ4685	CM	3.42	3.6	3.78	50	7.5	2
MMSZ4686	CN	3.71	3.9	4.1	50	5	2
MMSZ4687	CP	4.09	4.3	4.52	50	4	2
MMSZ4688	CT	4.47	4.7	4.94	50	10	3
MMSZ4689	CU	4.85	5.1	5.36	50	10	3
MMSZ4690	CV	5.32	5.6	5.88	50	10	4
MMSZ4691	CA	5.89	6.2	6.51	50	10	5
MMSZ4692	CX	6.46	6.8	7.14	50	10	5.1
MMSZ4693	CY	7.13	7.5	7.88	50	10	5.7
MMSZ4694	CZ	7.79	8.2	8.61	50	1	6.2
MMSZ4695	DC	8.27	8.7	9.14	50	1	6.6
MMSZ4696	DD	8.65	9.1	9.56	50	1	6.9
MMSZ4697	DE	9.5	10	10.5	50	1	7.6
MMSZ4698	DF	10.5	11	11.6	50	0.05	8.4
MMSZ4699	DH	11.4	12	12.6	50	0.05	9.1
MMSZ4700	DJ	12.4	13	13.7	50	0.05	9.8
MMSZ4701	DK	13.3	14	14.7	50	0.05	10.6
MMSZ4702	DM	14.3	15	15.8	50	0.05	11.4
MMSZ4703	DN	15.2	16	16.8	50	0.05	12.1
MMSZ4704	DP	16.2	17	17.9	50	0.05	12.9
MMSZ4705	DT	17.1	18	18.9	50	0.05	13.6
MMSZ4706	DU	18.1	19	20	50	0.05	14.4
MMSZ4707	DV	19	20	21	50	0.01	15.2
MMSZ4708	DA	20.9	22	23.1	50	0.01	16.7
MMSZ4709	DZ	22.8	24	25.2	50	0.01	18.2
MMSZ4710	DY	23.8	25	26.3	50	0.01	19
MMSZ4711	EA	25.7	27	28.4	50	0.01	20.4
MMSZ4712	EC	26.6	28	29.4	50	0.01	21.2
MMSZ4713	ED	28.5	30	31.5	50	0.01	22.8
MMSZ4714	EE	31.4	33	34.7	50	0.01	25
MMSZ4715	EF	34.2	36	37.8	50	0.01	27.3
MMSZ4716	EH	37.1	39	41	50	0.01	29.6
MMSZ4717	EJ	40.9	43	45.2	50	0.01	32.6

(1) Measured with device junction in thermal equilibrium

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123



The recommended mounting pad size

